MOLDING DIE, RESIN MOLDING APPARATUS, AND METHOD FOR PRODUCING RESIN MOLDED PRODUCT

ABSTRACT

A molding die includes one die and the other die that is arranged opposing the one die and has a cavity where a release film is arranged. The other die includes a main surface member that forms a main surface of the cavity and a side surface member that forms a side surface of the cavity. On an opposing surface of the side surface member opposing the one die, a release film adsorption hole that adsorbs the release film is formed including a plurality of first suction holes and a second suction hole that connects adjacent first suction holes. On the opposing surface, the first suction hole is larger than the second suction hole in the direction perpendicular to the direction in which the second suction hole extends to connect adjacent first suction holes.

FIG. 3